ABSTRACT

The present invention provides a mounting device capable of highly reliable mounting a plurality of electrical components using an adhesive agent. The present invention is a mounting device including a thermocompression bonding head 4 having a pressure bonding member 6 made of a predetermined elastomer provided in a head main body 5, and the mounting device is constructed such that an IC chip 20 placed on a wiring board 10 is pressed by the pressure bonding member 6 at a predetermined pressure, and further includes a pressing force adjusting mechanism for adjusting pressing force corresponding to a region on a pressure bonding surface 6a of the pressure bonding member 6. A pressing force adjusting mechanism can be used in which a plurality of pressing force adjusting frames 5a are provided in the head main body 5, and the pressure bonding member 6 is disposed inside these pressing force adjusting frames 5a.